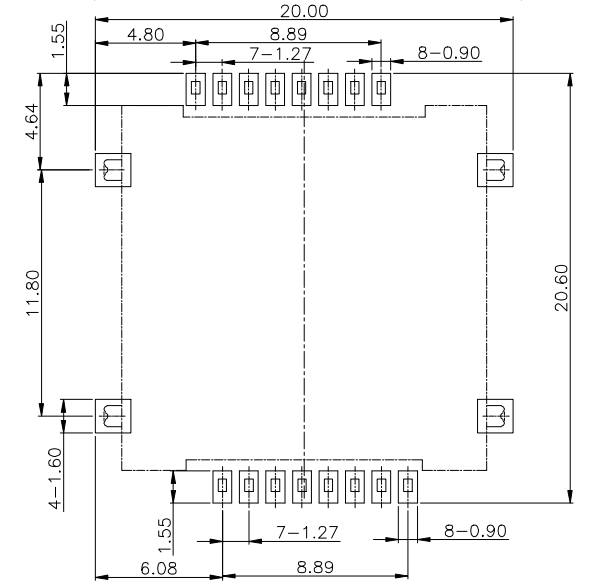
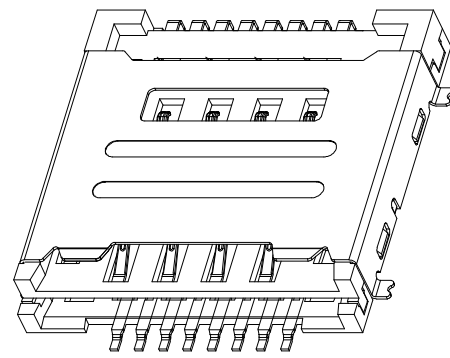
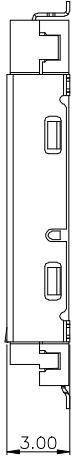
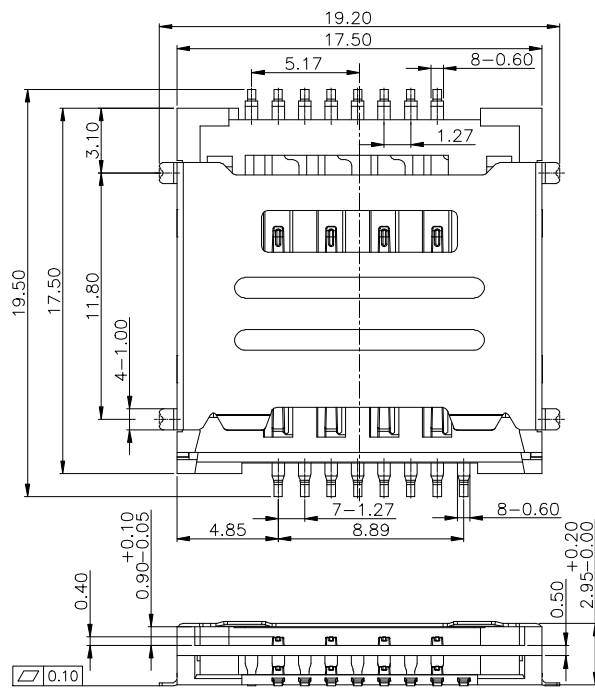
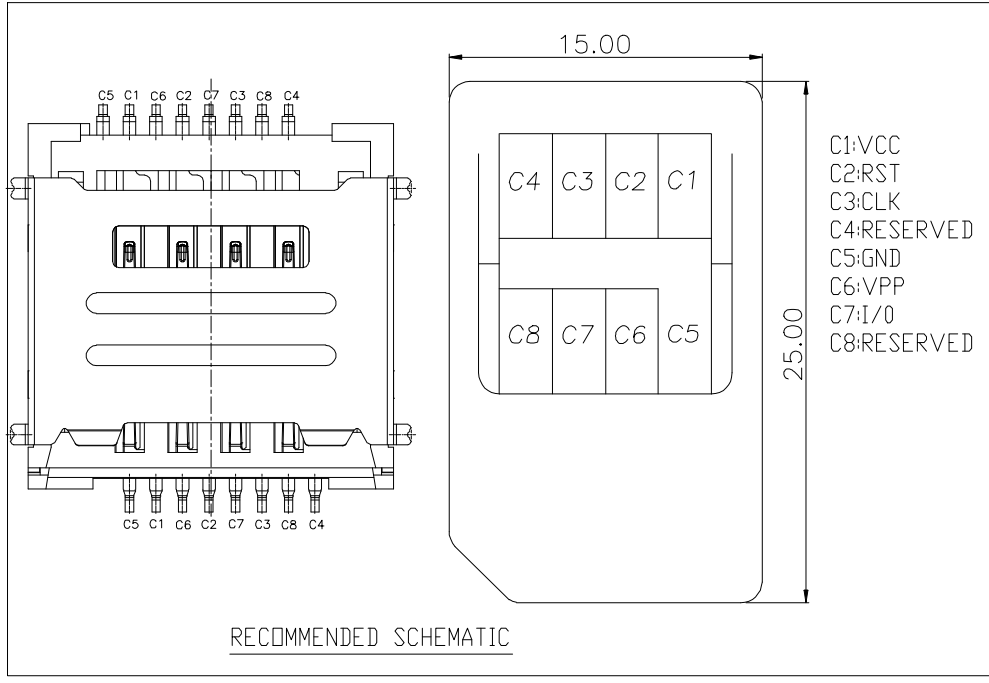


REV.	DATE	MODIFICATION	APPROVER
A	20150527	NEW	Jason_Lee



RECOMMENDED PC BOARD LAYOUT  
TOLFRANCE: +0.05[ TOP VIFW ]



NOTE:  
 1.MATERIAL:  
 HOUSING:LCP BLACK UL94V-0  
 CONTACT: COPPER ALLOY(C5210)  
 SHELL:SUS304  
 2.PLATED  
 CONTACT AREA GOLD FLASH PLATED OVER NI  
 SOLDER TAIL 100u\*MIN SN PLATED OVER NI  
 SHELL:NICKEL 30u\*PLATED OVER ALL,GOLD  
 FLASH PLATED ON SOLDER AREA  
 3.SPECIFICATION NOTES:  
 CONTACT RESISTANCE:100 milliohms MAX  
 CURRENT RATING:0.5A  
 VOLTAGE RATING:30V  
 DIELECTRIC WITHSTANDING VOLTAGE:300V AC

GENERAL TOLERANCE		UNITS mm	NAME:		DUAL SIM CARD 8P			深圳市爱特姆科技有限公司 SHENZHEN ATOM TECHNOLOGY CO.,LTD.		
SELECT	<input checked="" type="checkbox"/>		MAT'L	PART NO:		DUAL SIM CARD 8P SMT			TITLE:	
TOL	1 2 3	SI31C-08200		H=3.0mm						
DN.	X.XXX	±0.10±0.05±0.15	APPD:		Jason			DWG NO.		
	X.XX	±0.15±0.13±0.25	FINISH					ATOM-A02551		
	X.X	±0.20±0.25±0.5	Q'TY		Vicky			SCALE SHEET REV		
	X.	±0.30±0.38±1.00	DR:		JACK			1:1 1/2 A		
ANGLE	±2°									